



Major Ratings and Characteristics

$I_{F(AV)}$	3A
V_{RRM}	100V
I_{FSM}	100A
I_R	500uA
V_F	0.85V
T_{JMAX}	150°C

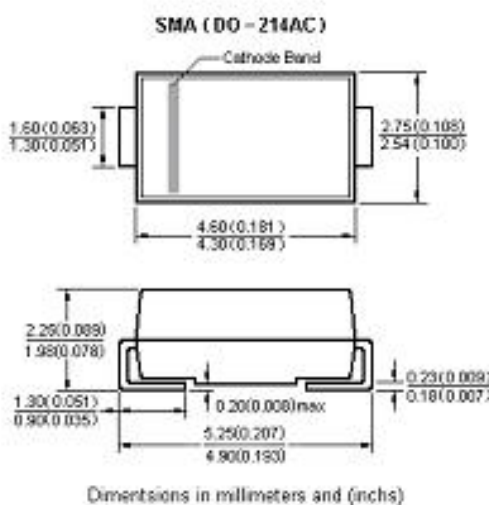


Features

- Low profile package
- Ideal for automated placement
- Ultrafast reverse recovery time
- Low power losses, high efficiency
- Low forward voltage drop
- High surge capability
- High temperature soldering:
260°C/10 seconds at terminals
- Component in accordance to
RoHS 2002/95/1 and WEEE 2002/96/EC

Mechanical Data

- Case: JEDEC DO-214AC molded plastic body over passivated chip
- Terminals: Solder plated, solderable per J-STD-002B and JESD22-B102D
- Polarity: Laser band denotes cathode end



Maximum Ratings & Thermal Characteristics & Electrical Characteristics

(TA = 25 °C unless otherwise noted)

Type Number	SYMBOL	SS310	unit
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	100	V
Maximum RMS Voltage	V_{RMS}	70	V
Maximum DC blocking Voltage	V_{DC}	100	V
Maximum Average Forward Rectified Current .at TA =55°C	$I_{F(AV)}$	3	A
Peak Forward Surge Current 8.3ms single half sine-wave superimposed on rated load (JEDEC method)	I_{FSM}	100	A
Maximum Forward Voltage at 1.5A DC	V_F	0.85	V
Maximum DC Reverse Current @TA =25°C	I_R	0.5	mA
At rated DC blocking voltage @TA=100°C		40	
Typical Junction Capacitance (Note1)	C_j	300	pF
Typical Thermal Resistance (Note 2)	$R_{(JA)}$	85	°C /W
Storage Temperature	T_{STG}	-55 to +150	°C
Operation Junction Temperature	T_J	-55 to +125	°C



Schottky rectifier

FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

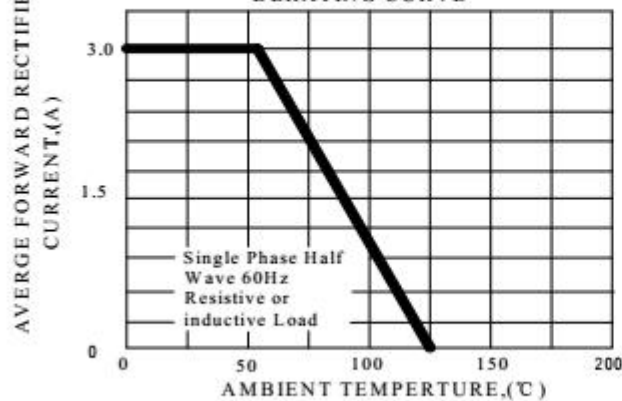


FIG.3-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

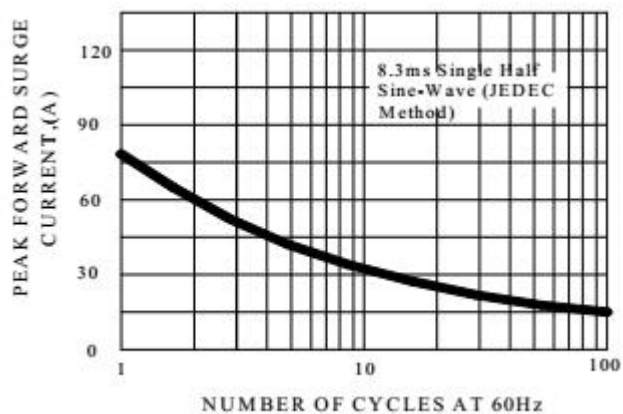


FIG.2-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

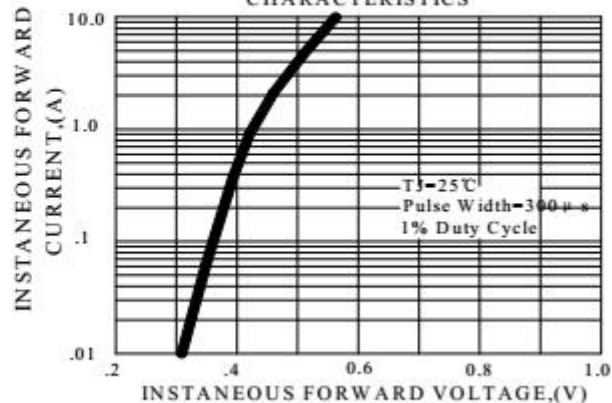


FIG.4-TYPICAL REVERSE CHARACTERISTICS

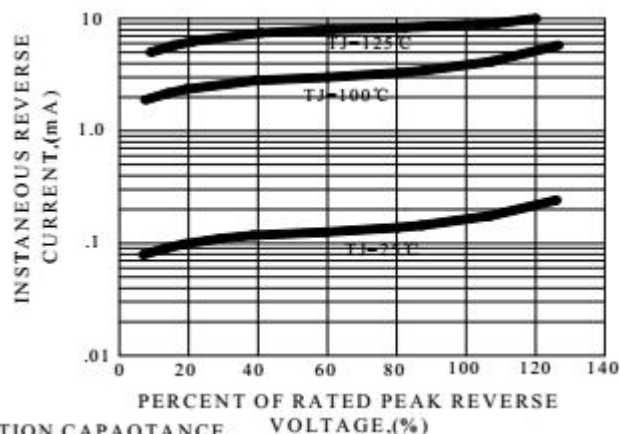


FIG.5-TYPICAL JUNCTION CAPACITANCE

